

ABSTRACT OF THE DISCLOSURE

An object of the invention is to provide a mechanism and method for supporting a substrate to be coated with a film, which enables transporting a substrate coated with a thin film, out of a film forming apparatus without damaging the substrate or the thin film. A support mechanism is provided with a stage, a shaft member, and support pins. When the substrate is placed on the stage which is held in a horizontal state, the shaft member is rotated so that the stage is lifted up to a film forming position where a substrate bearing surface of the stage becomes a substantially vertical. After film formation has been carried out at the film forming position, an actuator is driven so as to move the support pins provided in the stage. Accordingly, cracks and chips in the substrate as well as peeling-off of the thin film can be almost completely prevented.